

高性能PTFE陶瓷高频高速基板

HIGH PERFORMANCE CERAMIC-FILLED PTFE HIGH-FREQUENCY AND HIGH-SPEED CCL



广东康赛通技术有限公司
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前言

广东康赛通技术有限公司是世界级领先的高性能电介质、高频高速层压CCL基板研发和生产一体的企业，产品广泛应用于航空航天、相控阵雷达和汽车雷达传感器、卫星通信、移动通信和互联网设备、无线与有线(数字)基础设施中的高级微波射频芯片封装印刷电路及其相关应用。

作为高性能PTFE陶瓷高频高速覆铜板的专业生产制造商，康赛通不仅提供先进的陶瓷填充PTFE复合基板材料，更能根据客户需求提供从基材到成品的全链路制造解决方案。业务范围涵盖PCB(单层/多层板)生产至完整PCBA制造，包括SMT贴装及其他相关的配套加工服务。

PREFACE

GUANGDONG KANSAITOM TECHNOLOGY LTD. is a world-leading enterprise specializing in the R&D and production of high-performance dielectric and high-frequency & high-speed CCL substrates. Our products are widely used in aerospace, phased array radar and automotive radar sensors, satellite communications, mobile communications and internet equipment, as well as microwave RF chip packaging PCBs and related applications in wireless and wired (digital) infrastructure.

As a professional manufacturer of high-performance PTFE ceramic high-frequency & high-speed CCL, beyond supplying this advanced ceramic-filled PTFE composite laminates, KANSAITOM provides comprehensive manufacturing solutions tailored to client requirements. Our capabilities extend to PCB fabrication (single and multi-layer boards) to complete PCBA manufacturing, including SMT assembly and other related processing needs.



高性能PTFE陶瓷高频高速基板

High Performance Ceramic-Filled PTFE High-Frequency and High-Speed CCL

产品 Product	介电常数Dk Dielectric Constant	介电损耗Df Dissipation Factor	介电常数温度系数TCDK -50~150°C Thermal Coefficient of Dielectric Constant	表面电阻 Surface Resistivity	体积电阻率 Volume Resistivity	铜箔剥离强度 Copper Peel Strength	热膨胀系数CTE -55~288°C Coefficient of Thermal Expansion			吸水率 Moisture Absorption	密度 Density	热导率 Thermal Conductivity	热分解温度Td Thermal Decomposition Temperature	击穿电压 Breakdown Voltage	阻燃等级 Flammability
	10GHz	10GHz	ppm/°C	MΩ	MΩ-cm	N/mm(pli)	x	y	z	%	g/cm³	W/(M-K)	5% (°C)	kV	UL94
KCFP220 PTFE陶瓷 Ceramic	2.2±0.04	0.0018	50	2x10 ⁶	1.7x10 ⁷	1.6 (9)	37	42	48	0.03	1.5	0.3	530	45	V-0
KCFP265 PTFE陶瓷 Ceramic	2.65±0.04	0.0008	22	1.5x10 ⁶	1.4x10 ⁷	1.8 (10)	31	37	45	0.03	2.0	0.45	530	45	V-0
KCFP294 PTFE陶瓷 Ceramic	2.94±0.04	0.0005	31	1.2x10 ⁷	1.3x10 ⁷	2.2 (13)	18	19	32	0.04	2.2	0.5	526	45	V-0
KCFP300 PTFE陶瓷 Ceramic	3.0±0.04	0.0004	33	1x10 ⁷	1x10 ⁷	2.2 (13)	16	17	25	0.04	2.2	0.5	526	45	V-0
KCFP350 PTFE陶瓷 Ceramic	3.5±0.05	0.0013	-47	1.7x10 ⁶	1x10 ⁶	3 (17)	12	12	24	0.05	2.3	0.63	520	45	V-0
KCFP440 PTFE陶瓷 Ceramic	4.4±0.07	0.0010	-61	1.7x10 ⁶	1.5x10 ⁶	3 (17)	18	18	29	0.03	2.5	0.7	514	45	V-0
KCFP615 PTFE陶瓷 Ceramic	6.15±0.15	0.0007	37	1x10 ⁶	1x10 ⁶	2.8 (16)	17	17	25	0.02	2.6	0.8	508	45	V-0
KCFP1020 PTFE陶瓷 Ceramic	10.2±0.2	0.0012	-332	1x10 ⁶	1x10 ⁶	2.8 (16)	13	11	17	0.04	3.1	0.9	500	45	V-0

注释:

- [1]: 介电常数测试标准: IPC-TM-650 2.5.5.5带状线
- [2]: 吸水率测试标准: IPC-TM-650 2.6.2.1 D24/23
- [3]: 导热率测试标准: ASTM D5470 80°C
- [4]: 剥离强度测试铜箔规格: 1/2oz. (18μm) 电解铜箔, Rz=1.0μm

Notes:

- [1]: Dielectric Constant Testing Standards: IPC-TM-650 2.5.5.5 Stripline Test
- [2]: Moisture Absorption Testing Standards: IPC-TM-650 2.6.2.1 D24/23
- [3]: Thermal Conductivity Testing Standards: ASTM D5470 80°C
- [4]: Peel Strength with Copper Foil specifications: 1/2oz. (18um) Electrodeposited Copper Foil, Rz=1.0um

标准厚度 Standard Thicknesses	标准尺寸 Standard Panel Sizes	标准铜箔 Standard Cladding
KCFP220 KCFP265 KCFP294 KCFP300 KCFP350 KCFP440 KCFP615 KCFP1020	5mil (0.127mm)±0.5mil (0.0127mm) 10mil (0.254mm)±0.7mil (0.01778mm) 20mil (0.508mm)±1mil (0.0254mm) 40mil (1.016mm)±2mil (0.0508mm)	12"x18" (305mm x 457mm) 18"x24" (457mm x 610mm)
		HTE/RTF/VLP/HVLP: 1/2oz (18μm) 电解铜箔 Electrodeposited Copper Foil 1oz (35μm) 电解铜箔 Electrodeposited Copper Foil



◎KCFP220高频材料

KCFP220 High Frequency Material

- 毫米波雷达系统 Millimeter-Wave Radar Systems
- 5G/6G基站AAU天线馈电网络 5G/6G Base Station AAU Antenna Feeder Networks
- 卫星通信相控阵天线 Satellite Communication Phased Array Antennas
- 高端AI服务器背板 High-End AI Server Backplanes

项目 Items	方向 Directions	KCFP220	单位 Units	测试条件 Test Conditions	测试方法 Test Method
介电常数Dk	-	2.2±0.04	-	10GHz	IPC-TM-650 2.5.5.5
介电损耗Df	-	0.0018	-	10GHz	IPC-TM-650 2.5.5.5
介电常数温漂系数 TCDk	-	50	ppm/°C	-50~150°C	IPC-TM-650 2.5.5.5
表面电阻 Surface Resistivity	X/Y	2x10 ⁶	MΩ	COND A	IPC 2.5.17.1
体积电阻率 Volume Resistivity	-	1.7x10 ⁷	MΩ·cm	COND A	IPC 2.5.17.1
吸水率 Moisture Absorption	-	0.03	%	D24/23	IPC-TM-650 2.6.2.1
热导率 Thermal conductivity	-	0.3	W/(M·K)	80°C	ASTM D5470
热膨胀系数 CTE	X	37	ppm/°C	-50~288°C	IPC-TM-650 2.4.41 IPC-TM-650 2.4.24
	Y	42			
	Z	48			
剥离强度 Copper Peel Strength	-	1.6 (9)	N/mm(pli)	1/2oz (18μm) 电解铜箔 Electrodeposited Copper Foil	IPC-TM-2.4.8
阻燃等级 Flammability	-	V-0	-	-	UL94



◎KCFP265高频材料

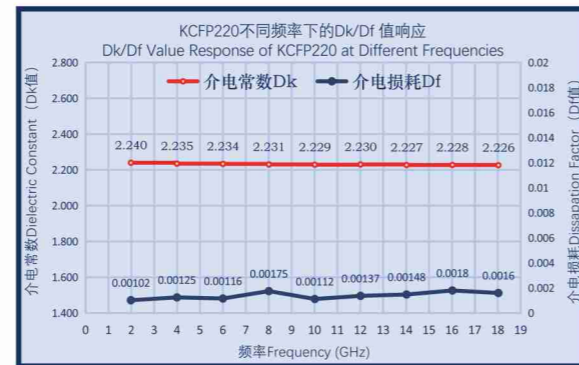
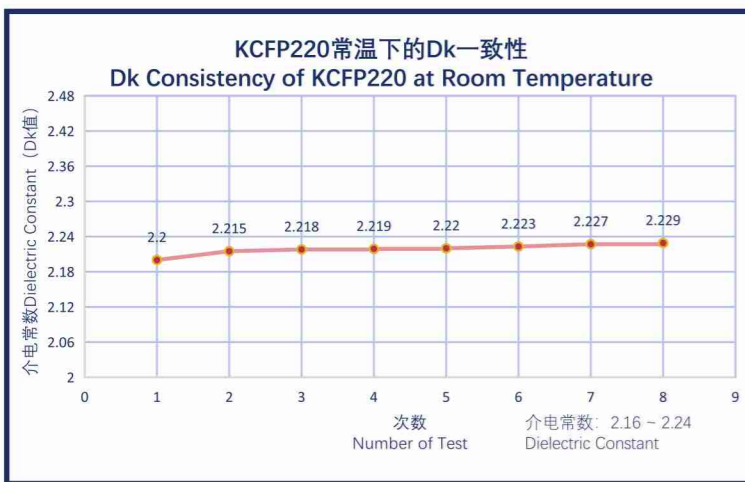
KCFP265 High Frequency Material

- 5G中高频段RRU射频模块 5G Mid-to-High Frequency
- Band RRU RF Modules
- 高性能计算 (HPC) PCB中间层 HPC PCB Inner Layers
- 雷达前端电路 Radar Front-End Circuits

项目 Items	方向 Directions	KCFP265	单位 Units	测试条件 Test Conditions	测试方法 Test Method
介电常数Dk	-	2.65±0.04	-	10GHz	IPC-TM-650 2.5.5.5
介电损耗Df	-	0.0008	-	10GHz	IPC-TM-650 2.5.5.5
介电常数温漂系数 TCDk	-	22	ppm/°C	-50~150°C	IPC-TM-650 2.5.5.5
表面电阻 Surface Resistivity	X/Y	1.5x10 ⁶	MΩ	COND A	IPC 2.5.17.1
体积电阻率 Volume Resistivity	-	1.4x10 ⁷	MΩ·cm	COND A	IPC 2.5.17.1
吸水率 Moisture Absorption	-	0.03	%	D24/23	IPC-TM-650 2.6.2.1
热导率 Thermal conductivity	-	0.45	W/(M·K)	80°C	ASTM D5470
热膨胀系数 CTE	X	31	ppm/°C	-50~288°C	IPC-TM-650 2.4.41 IPC-TM-650 2.4.24
	Y	37			
	Z	45			
剥离强度 Copper Peel Strength	-	1.8 (10)	N/mm(pli)	1/2oz (18μm) 电解铜箔 Electrodeposited Copper Foil	IPC-TM-2.4.8
阻燃等级 Flammability	-	V-0	-	-	UL94

◎KCFP220电性能图表

KCFP220 Electrical Performance Chart

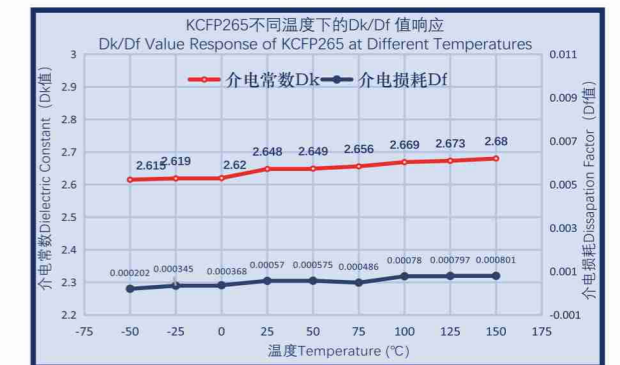
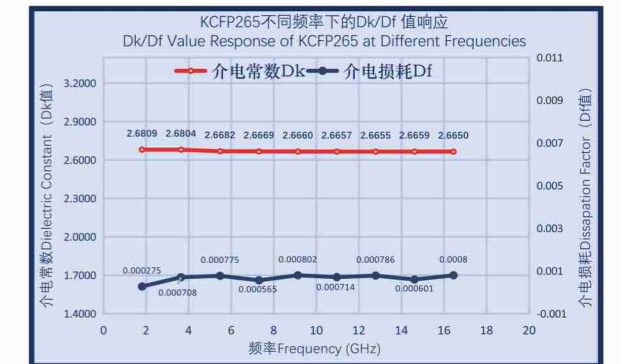
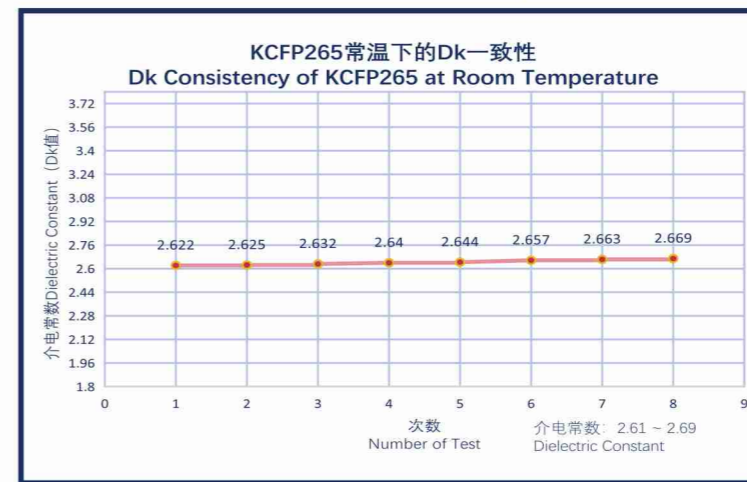


频率稳定性: 用带状线法测试材料在0~20GHz频率内, KCFP220的介电常数与损耗稳定, 保持超低损耗值。
Frequency stability: Tested by the stripline method, the dielectric constant and dissipation of KCFP220 remain stable within the frequency range of 0~20 GHz, maintaining an ultra-low dissipation value.

温度稳定特性: KCFP220在-55~150°C范围内的TCDk为50PPM/°C左右, 变化极小。
Temperature stability: The TCDk of KCFP220 is approximately 50 PPM/°C within the range of -55~150°C, with an extremely small variation.

◎KCFP265电性能图表

KCFP265 Electrical Performance Chart



频率稳定性: 用带状线法测试材料在0~20GHz频率内, KCFP265的介电常数与损耗稳定, 保持超低损耗值。
Frequency stability: Tested by the stripline method, the dielectric constant and dissipation of KCFP265 remain stable within the frequency range of 0~20 GHz, maintaining an ultra-low dissipation value.

温度稳定特性: KCFP265在-55~150°C范围内的TCDk为22PPM/°C左右, 变化极小。
Temperature stability: The TCDk of KCFP265 is approximately 22 PPM/°C within the range of -55~150°C, with an extremely small variation.



◎KCFP294高频材料
KCFP294 High Frequency Material

- 相控阵天线阵列板 Phased Array Antenna Array Boards
- 贴片天线基板 Patch Antenna Substrates
- 功率放大器 Power Amplifiers

项目 Items	方向 Directions	KCFP294	单位 Units	测试条件 Test Conditions	测试方法 Test Method
介电常数Dk	-	2.94±0.04	-	10GHz	IPC-TM-650 2.5.5.5
介电损耗Df	-	0.0005	-	10GHz	IPC-TM-650 2.5.5.5
介电常数温漂系数 TCDk	-	31	ppm/°C	-50~150°C	IPC-TM-650 2.5.5.5
表面电阻 Surface Resistivity	X/Y	1.2x10 ⁷	MΩ	COND A	IPC 2.5.17.1
体积电阻率 Volume Resistivity	-	1.3x10 ⁷	MΩ-cm	COND A	IPC 2.5.17.1
吸水率 Moisture Absorption	-	0.04	%	D24/23	IPC-TM-650 2.6.2.1
热导率 Thermal conductivity	-	0.5	W/(M-K)	80°C	ASTM D5470
热膨胀系数 CTE	X	18	ppm/°C	-50~288°C	IPC-TM-650 2.4.41 IPC-TM-650 2.4.24
	Y	19			
	Z	32			
剥离强度 Copper Peel Strength	-	2.2 (13)	N/mm(pli)	1/2oz (18μm) 电解铜箔 Electrodeposited Copper Foil	IPC-TM-2.4.8
阻燃等级 Flammability	-	V-0	-	-	UL94

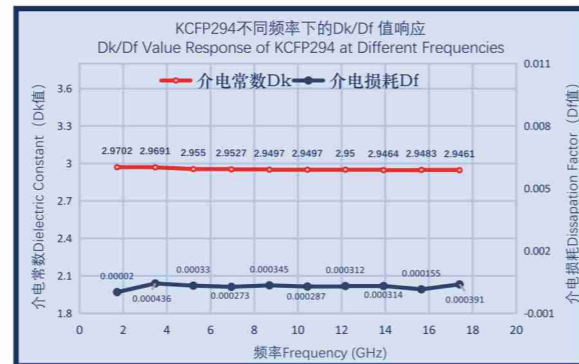
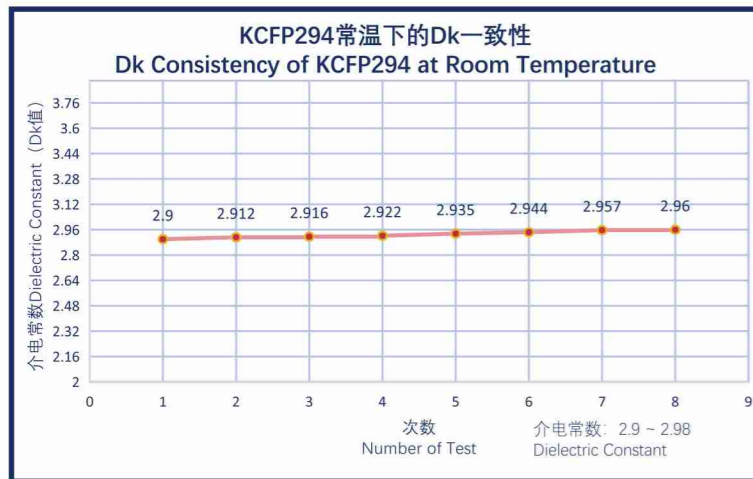


◎KCFP300高频材料
KCFP300 High Frequency Material

- 车载毫米波雷达 Automotive Millimeter-Wave Radar
- 5G宏站射频单元 5G Macro Base Station RF Units
- 工业级无线传感器网络 Industrial Wireless Sensor Networks

项目 Items	方向 Directions	KCFP300	单位 Units	测试条件 Test Conditions	测试方法 Test Method
介电常数Dk	-	3.0±0.04	-	10GHz	IPC-TM-650 2.5.5.5
介电损耗Df	-	0.0004	-	10GHz	IPC-TM-650 2.5.5.5
介电常数温漂系数 TCDk	-	33	ppm/°C	-50~150°C	IPC-TM-650 2.5.5.5
表面电阻 Surface Resistivity	X/Y	1x10 ⁷	MΩ	COND A	IPC 2.5.17.1
体积电阻率 Volume Resistivity	-	1x10 ⁷	MΩ-cm	COND A	IPC 2.5.17.1
吸水率 Moisture Absorption	-	0.04	%	D24/23	IPC-TM-650 2.6.2.1
热导率 Thermal conductivity	-	0.5	W/(M-K)	80°C	ASTM D5470
热膨胀系数 CTE	X	16	ppm/°C	-50~288°C	IPC-TM-650 2.4.41 IPC-TM-650 2.4.24
	Y	17			
	Z	25			
剥离强度 Copper Peel Strength	-	2.2 (13)	N/mm(pli)	1/2oz (18μm) 电解铜箔 Electrodeposited Copper Foil	IPC-TM-2.4.8
阻燃等级 Flammability	-	V-0	-	-	UL94

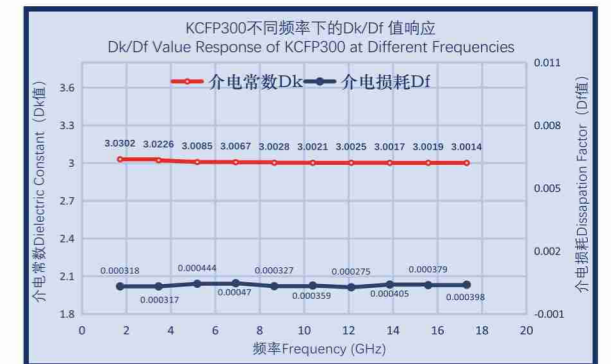
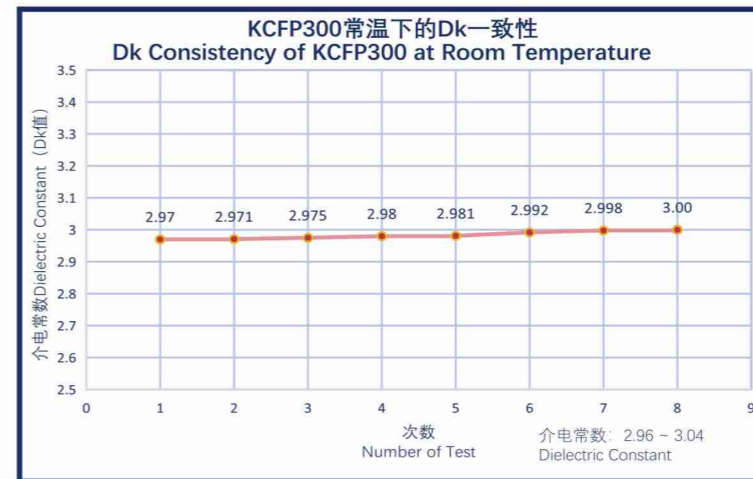
◎KCFP294电性能图表
KCFP294 Electrical Performance Chart



频率稳定性: 用带状线法测试材料在0~20GHz频率内, KCFP294的介电常数与损耗稳定, 保持超低损耗值。
Frequency stability: Tested by the stripline method, the dielectric constant and dissipation of KCFP294 remain stable within the frequency range of 0~20 GHz, maintaining an ultra-low dissipation value.

温度稳定特性: KCFP294在-55~150°C范围内的TCDk为31PPM/°C左右, 变化极小。
Temperature stability: The TCDk of KCFP294 is approximately 31 PPM/°C within the range of -55~150°C, with an extremely small variation.

◎KCFP300电性能图表
KCFP300 Electrical Performance Chart



频率稳定性: 用带状线法测试材料在0~20GHz频率内, KCFP300的介电常数与损耗稳定, 保持超低损耗值。
Frequency stability: Tested by the stripline method, the dielectric constant and dissipation of KCFP300 remain stable within the frequency range of 0~20 GHz, maintaining an ultra-low dissipation value.

温度稳定特性: KCFP300在-55~150°C范围内的TCDk为33PPM/°C左右, 变化极小。
Temperature stability: The TCDk of KCFP300 is approximately 33 PPM/°C within the range of -55~150°C, with an extremely small variation.

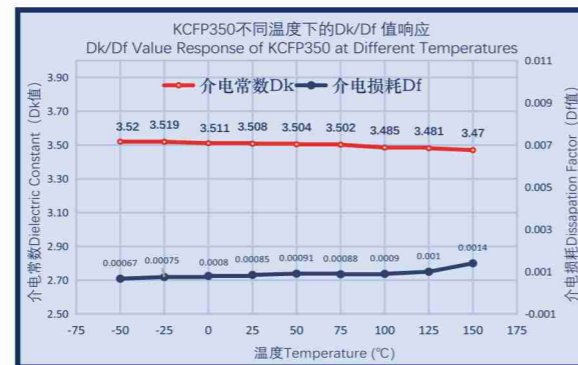
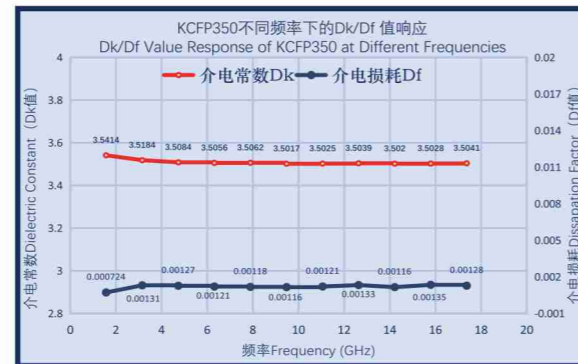
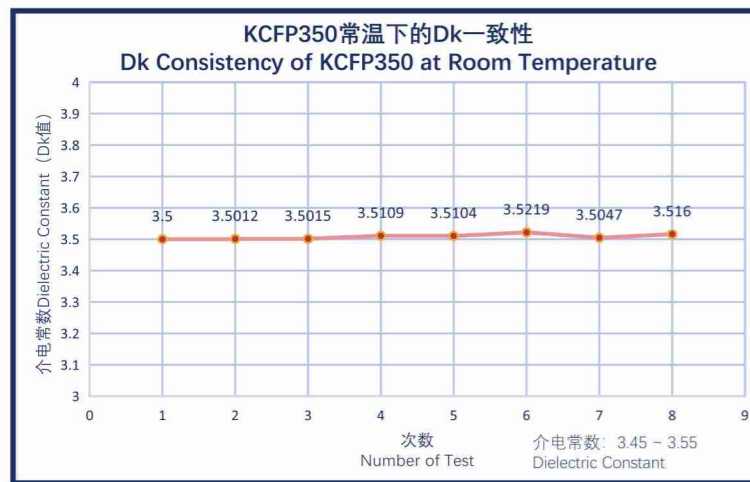


◎KCFP350高频材料 KCFP350 High Frequency Material

- 中高频通信设备 Mid-to-High Frequency Communication Equipment
- 测试测量仪器PCB Test & Measurement Equipment PCBs
- 高端消费电子射频前端 RF Front-End Modules for High-End Consumer Electronics

项目 Items	方向 Directions	KCFP350	单位 Units	测试条件 Test Conditions	测试方法 Test Method
介电常数Dk	-	3.5±0.05	-	10GHz	IPC-TM-650 2.5.5.5
介电损耗Df	-	0.0013	-	10GHz	IPC-TM-650 2.5.5.5
介电常数温漂系数 TCDk	-	-47	ppm/°C	-50~150°C	IPC-TM-650 2.5.5.5
表面电阻 Surface Resistivity	X/Y	1.7x10 ⁶	MΩ	COND A	IPC 2.5.17.1
体积电阻率 Volume Resistivity	-	1x10 ⁶	MΩ·cm	COND A	IPC 2.5.17.1
吸水率 Moisture Absorption	-	0.05	%	D24/23	IPC-TM-650 2.6.2.1
热导率 Thermal conductivity	-	0.63	W/(M·K)	80°C	ASTM D5470
热膨胀系数 CTE	X	12	ppm/°C	-50~288°C	IPC-TM-650 2.4.41 IPC-TM-650 2.4.24
	Y	12			
	Z	24			
剥离强度 Copper Peel Strength	-	3 (17)	N/mm(pli)	1/2oz (18μm) 电解铜箔 Electrodeposited Copper Foil	IPC-TM-2.4.8
阻燃等级 Flammability	-	V-0	-	-	UL94

◎KCFP350电性能图表 KCFP350 Electrical Performance Chart



频率稳定性: 用带状线法测试材料在0~20GHz频率内, KCFP350的介电常数与损耗稳定, 保持超低损耗值。
Frequency stability: Tested by the stripline method, the dielectric constant and dissipation of KCFP350 remain stable within the frequency range of 0~20 GHz, maintaining an ultra-low dissipation value.

温度稳定特性: KCFP350在-55~150°C范围内的TCDk为-47PPM/°C左右, 变化极小。
Temperature stability: The TCDk of KCFP350 is approximately -47 PPM/°C within the range of -55~150°C, with an extremely small variation.

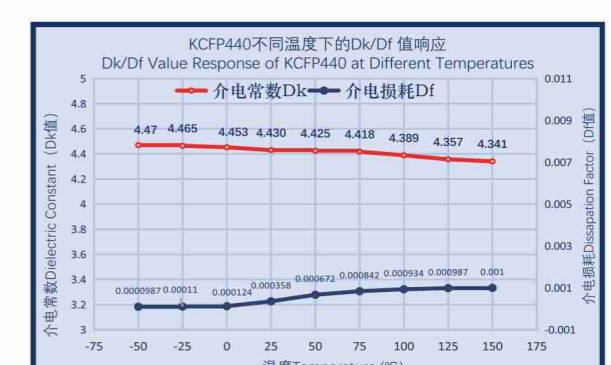
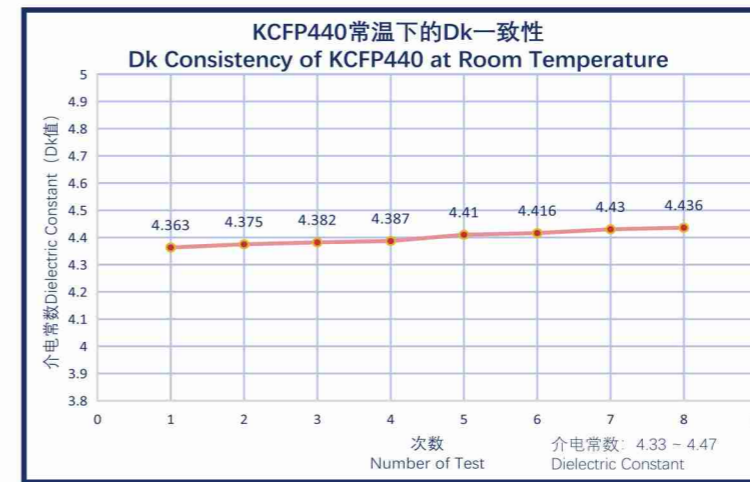


◎KCFP440高频材料 KCFP440 High Frequency Material

- 中高速数字电路板Mid-to-High Speed Digital Circuit Boards
- 工业控制主板Industrial Control Motherboards
- 汽车电子ECUAutomotive Electronic Control Units (ECUs)

项目 Items	方向 Directions	KCFP440	单位 Units	测试条件 Test Conditions	测试方法 Test Method
介电常数Dk	-	4.4±0.07	-	10GHz	IPC-TM-650 2.5.5.5
介电损耗Df	-	0.0010	-	10GHz	IPC-TM-650 2.5.5.5
介电常数温漂系数 TCDk	-	-61	ppm/°C	-50~150°C	IPC-TM-650 2.5.5.5
表面电阻 Surface Resistivity	X/Y	1.7x10 ⁵	MΩ	COND A	IPC 2.5.17.1
体积电阻率 Volume Resistivity	-	1.5x10 ⁵	MΩ·cm	COND A	IPC 2.5.17.1
吸水率 Moisture Absorption	-	0.03	%	D24/23	IPC-TM-650 2.6.2.1
热导率 Thermal conductivity	-	0.7	W/(M·K)	80°C	ASTM D5470
热膨胀系数 CTE	X	18	ppm/°C	-50~288°C	IPC-TM-650 2.4.41 IPC-TM-650 2.4.24
	Y	18			
	Z	29			
剥离强度 Copper Peel Strength	-	3 (17)	N/mm(pli)	1/2oz (18μm) 电解铜箔 Electrodeposited Copper Foil	IPC-TM-2.4.8
阻燃等级 Flammability	-	V-0	-	-	UL94

◎KCFP440电性能图表 KCFP440 Electrical Performance Chart



频率稳定性: 用带状线法测试材料在0~20GHz频率内, KCFP440的介电常数与损耗稳定, 保持超低损耗值。
Frequency stability: Tested by the stripline method, the dielectric constant and dissipation of KCFP440 remain stable within the frequency range of 0~20 GHz, maintaining an ultra-low dissipation value.

温度稳定特性: KCFP440在-55~150°C范围内的TCDk为-61PPM/°C左右, 变化极小。
Temperature stability: The TCDk of KCFP440 is approximately -61 PPM/°C within the range of -55~150°C, with an extremely small variation.



◎ KCFP615 高频材料
KCFP615 High Frequency Material

- 高功率射频电路 High-Power RF Circuits
- 微波滤波器与谐振器 Microwave Filters and Resonators
- 毫米波前端模组 Millimeter-Wave Front-End Modules

项目 Items	方向 Directions	KCFP615	单位 Units	测试条件 Test Conditions	测试方法 Test Method
介电常数Dk	-	6.15±0.15	-	10GHz	IPC-TM-650 2.5.5.5
介电损耗Df	-	0.0007	-	10GHz	IPC-TM-650 2.5.5.5
介电常数温漂系数 TCDk	-	37	ppm/°C	-50~150°C	IPC-TM-650 2.5.5.5
表面电阻 Surface Resistivity	X/Y	1x10 ⁵	MΩ	COND A	IPC 2.5.17.1
体积电阻率 Volume Resistivity	-	1x10 ⁵	MΩ-cm	COND A	IPC 2.5.17.1
吸水率 Moisture Absorption	-	0.02	%	D24/23	IPC-TM-650 2.6.2.1
热导率 Thermal conductivity	-	0.8	W/(M-K)	80°C	ASTM D5470
热膨胀系数 CTE	X	17	ppm/°C	-50~288°C	IPC-TM-650 2.4.41 IPC-TM-650 2.4.24
	Y	17			
	Z	25			
剥离强度 Copper Peel Strength	-	2.8 (16)	N/mm(pli)	1/2oz (18μm) 电解铜箔 Electrodeposited Copper Foil	IPC-TM-2.4.8
阻燃等级 Flammability	-	V-0	-	-	UL94

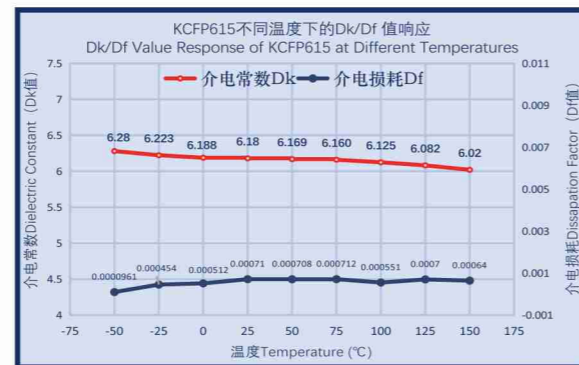
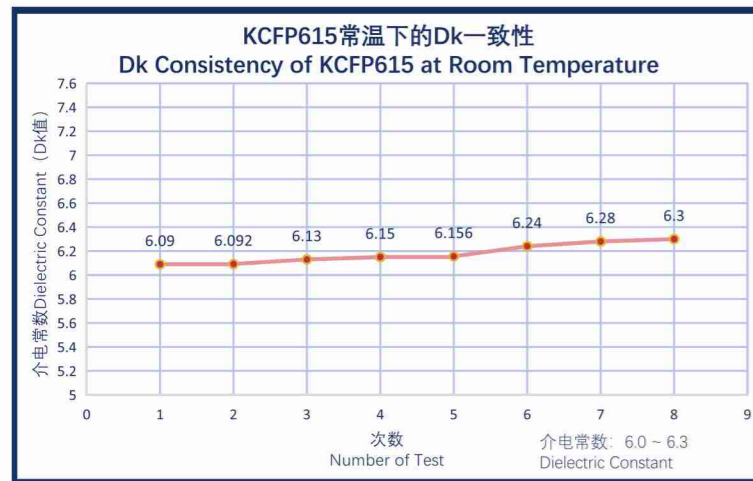


◎ KCFP1020 高频材料
KCFP1020 High Frequency Material

- 高功率射频电路 High-Power RF Circuits
- 微波滤波器与谐振器 Microwave Filters and Resonators
- 毫米波前端模组 Millimeter-Wave Front-End Modules

项目 Items	方向 Directions	KCFP1020	单位 Units	测试条件 Test Conditions	测试方法 Test Method
介电常数Dk	-	10.2±0.2	-	10GHz	IPC-TM-650 2.5.5.5
介电损耗Df	-	0.0012	-	10GHz	IPC-TM-650 2.5.5.5
介电常数温漂系数 TCDk	-	-332	ppm/°C	-50~150°C	IPC-TM-650 2.5.5.5
表面电阻 Surface Resistivity	X/Y	1x10 ⁵	MΩ	COND A	IPC 2.5.17.1
体积电阻率 Volume Resistivity	-	1x10 ⁵	MΩ-cm	COND A	IPC 2.5.17.1
吸水率 Moisture Absorption	-	0.04	%	D24/23	IPC-TM-650 2.6.2.1
热导率 Thermal conductivity	-	0.9	W/(M-K)	80°C	ASTM D5470
热膨胀系数 CTE	X	13	ppm/°C	-50~288°C	IPC-TM-650 2.4.41 IPC-TM-650 2.4.24
	Y	11			
	Z	17			
剥离强度 Copper Peel Strength	-	2.8 (16)	N/mm(pli)	1/2oz (18μm) 电解铜箔 Electrodeposited Copper Foil	IPC-TM-2.4.8
阻燃等级 Flammability	-	V-0	-	-	UL94

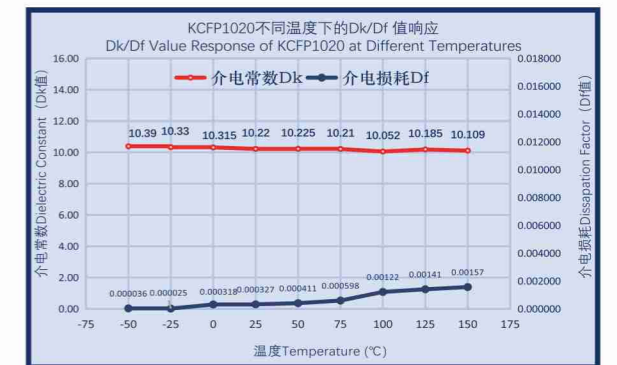
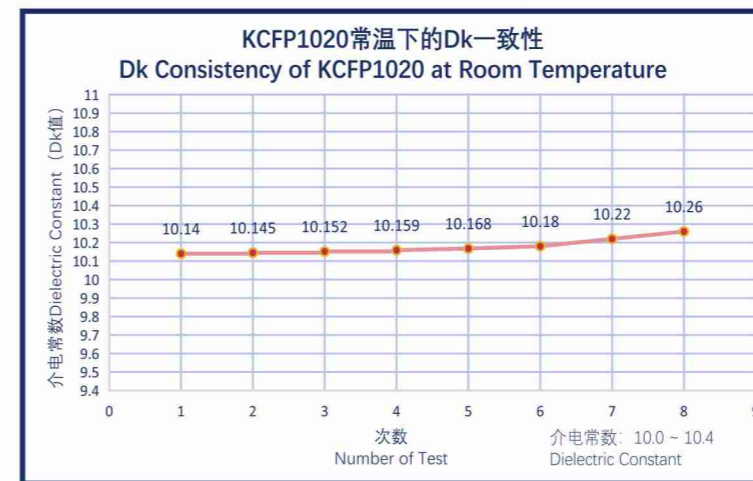
◎ KCFP615 电性能图表
KCFP615 Electrical Performance Chart



频率稳定性: 用带状线法测试材料在0~20GHz频率内, KCFP615的介电常数与损耗稳定, 保持超低损耗值。
Frequency stability: Tested by the stripline method, the dielectric constant and dissipation of KCFP615 remain stable within the frequency range of 0~20 GHz, maintaining an ultra-low dissipation value.

温度稳定特性: KCFP615在-55~150°C范围内的TCDk为37PPM/°C左右, 变化极小。
Temperature stability: The TCDk of KCFP615 is approximately 37 PPM/°C within the range of -55~150°C, with an extremely small variation.

◎ KCFP1020 电性能图表
KCFP1020 Electrical Performance Chart



频率稳定性: 用带状线法测试材料在0~20GHz频率内, KCFP1020的介电常数与损耗稳定, 保持超低损耗值。
Frequency stability: Tested by the stripline method, the dielectric constant and dissipation of KCFP1020 remain stable within the frequency range of 0~20 GHz, maintaining an ultra-low dissipation value.

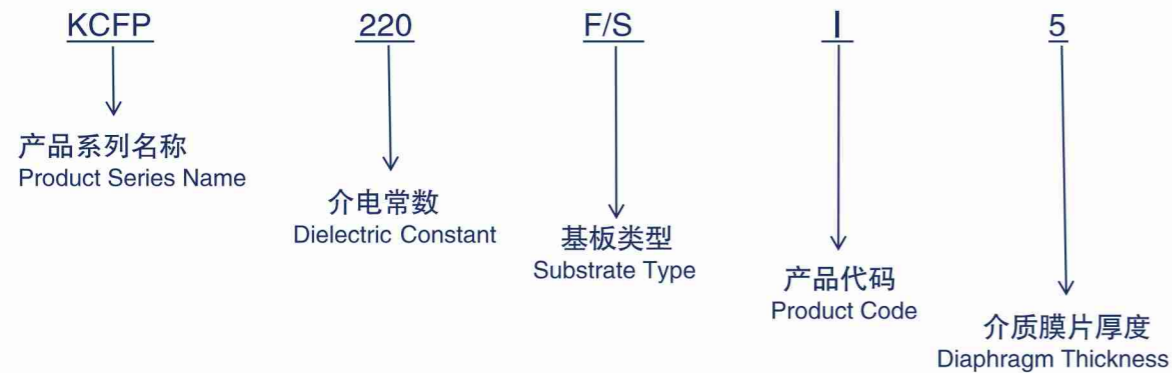
温度稳定特性: KCFP1020在-55~150°C范围内的TCDk为-332PPM/°C左右, 变化极小。
Temperature stability: The TCDk of KCFP1020 is approximately -332 PPM/°C within the range of -55~150°C, with an extremely small variation.



康赛通高频高速材料的命名规则
The Naming Conventions of KANSAITOM High-Frequency and High-Speed Materials

康赛通高频高速材料的命名规则

The Naming Conventions of KANSAITOM High-Frequency and High-Speed Materials



1. 产品系列名称 Product Series Name

KCFP: KANSAITOM

2. 介电常数 Dielectric Constant

220对应介电常数2.2

220 refers to dielectric constant 2.2

3. 基板类型 Substrate Type

"F"代表高频基板; "S"代表高速基板

"F" refers to high-frequency substrate; "S" refers to high-speed substrate

4. 产品代码 Product Code

"I"为产品代码

"I" refers to the product code

5. 介质膜片厚度 Diaphragm Thickness

5对应5mil, 为127 μ m (5 refers to 5 mil, equivalent to 127 μ m);

10对应10mil, 为254 μ m (10 refers to 10 mil, equivalent to 254 μ m);

20对应20mil, 为508 μ m (20 refers to 20 mil, equivalent to 508 μ m);

30对应30mil, 为762 μ m (30 refers to 30 mil, equivalent to 762 μ m);

40对应40mil, 为1016 μ m (40 refers to 40 mil, equivalent to 1016 μ m);

60对应60mil, 为1524 μ m (60 refers to 60 mil, equivalent to 1524 μ m)。



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产品具体信息 Product Details	产品牌号 (举例) Product Names (Samples)
KCFP220F I 5	5mil厚度 (127 μ m) 的Dk2.2一型高频基板 5mil Thickness (127 μ m) Dk 2.2 Type I High-Frequency Substrate
KCFP300F III 10	10mil厚度 (254 μ m) 的Dk3.0三型高频基板 10mil Thickness (254 μ m) Dk 3.0 Type III High-Frequency Substrate
KCFP1020S II 40	40mil厚度 (1016 μ m) 的Dk10.2二型高速基板 40 mil Thickness (1016 μ m) Dk10.2 Type II High-Speed Substrate

公司可以根据客户需要定制各种特定Dk值和厚度的CCL基板, 如需具体信息或有任何疑问, 请随时联系我们。

We can customize CCL substrates with specific Dk values and thicknesses according to customer requirements. Feel free to contact us for more information or any inquiries.

